ABSTRACT

A polishing composition of the present invention contains a water-soluble polymer having a hydrophilic group, and abrasive grains. A hydrophobic silicon-containing part after being polished with the polishing composition has a water contact angle lower than that of the hydrophobic silicon-containing part after being polished with another composition having the same makeup as the polishing composition except that the water-soluble polymer is not contained therein, and has a water contact angle of pr ably 57° or less. Examples of the water-soluble polymer include polysaccharides and alcohol compounds. Another polishing composition of the present invention contains abrasive grains having a silanol group, and a water-soluble polymer. When this polishing composition is left to stand for one day in an environment at a temperature of 25°C, the water-soluble polymer is adsorbed on the abrasive grains at 5,000 or more molecules per 1 μm^2 of surface area of the abrasive grains. Examples of this water-soluble polymer include nonionic compounds, such as polyethylene glycol, having a polyoxyalkylene chain.